

Supply Chain Explorer: Bonding tools

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Bonding tools

Bonding tools include die attach tools (to connect dies to lead frames or substrates), wire bonders (to make interconnects between lead frames and die pads), and advanced interconnect tools.

Variants

- Advanced interconnect tools
- Die attaching tools
- Wire bonding tools

Supplier countries (Variants)

- Belarus
- China (mainland)
- France
- Germany
- Japan
- Netherlands
- Singapore
- South Korea
- Taiwan
- United States

Notable supplier companies (Variants)

- ASM Pacific - China (mainland)
- Besi - Netherlands
- Canon - Japan
- DIAS Automation - China (mainland)
- Fasford Tech - Japan
- Hesse - Germany
- Hoson - China (mainland)
- KOSES - South Korea
- Kulicke & Soffa - Singapore
- PROTEC - South Korea
- Shinkawa - Japan
- SSP - South Korea